Specification Sheet

Customer Name	XXXX	CUST P/N	NA
Approval No.	PD	Temwell P/N	STSF-2515B30-S3030W
Lot No.		Date	2025.06.24
Description	SAW Filter (BandPass)	Version	A1

(1)Size Diagram（Unit：MM）
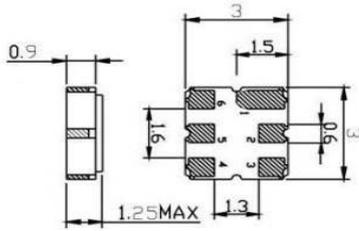
PinNo.	Description
2	Input
5	Output
1,3,4,6	Ground
Tolerance	±0.1mm

(2)Electrical Specifications

Item			Specification		
Parameter	MHz	Unit	Min.	Typical	Max.
Center Frequency	-	MHz	-	2515	-
Insertion Loss	2500-2530	dB	-	2.5	3.0
Ripple Deviation	2500-2530	dB	-	0.8	1.0
VAWR	2500-2530	-	-	1.5	2.0
Attenuation	DC-1000	dB	35	38	-
	1000-1700	dB	35	38	-
	1700-2346	dB	35	38	-
	3000-4000	dB	30	40	-
	4000-5380	dB	25	30	-
Operation Temperature	-40℃~+85℃	℃	-	-	-
Storage Temperature	-40℃~+85℃	℃	-	-	-
RF Power Dissipation	20	dBm	-	-	-
Remark	Note 1: Test Temperature: 25℃±2℃ 30				
	Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω				

(3)Test Circuit
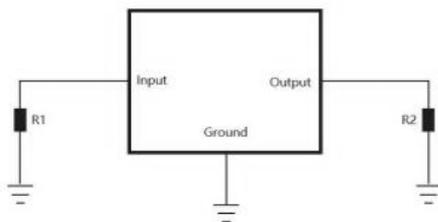
Port	Matching component
Input	R1: 50Ω
Output	R2: 50Ω

Figure 1. Electrical Characteristics: Frequency response
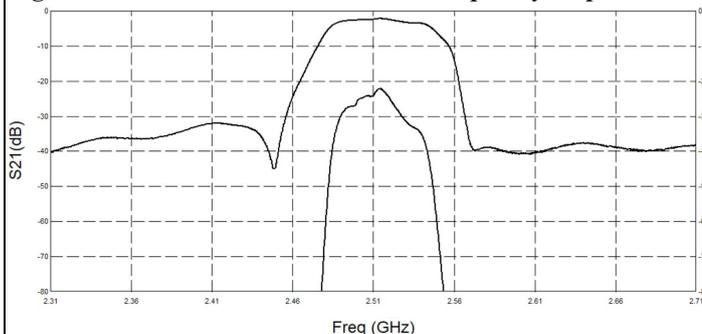
Figure 2. Electrical Characteristics: Wideband
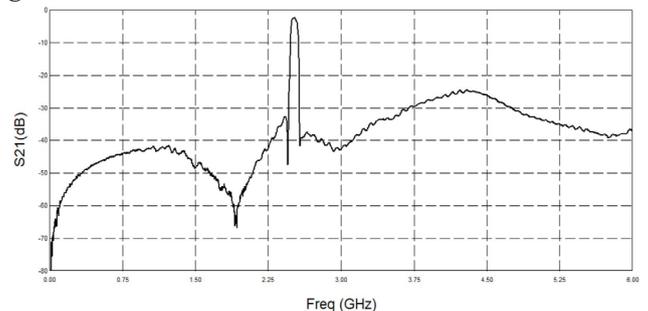
Approval	Supervisor	Designer
C. K. Chang	M. Y. Chen	F.L.Lai

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Recommended SMT Solder Profile
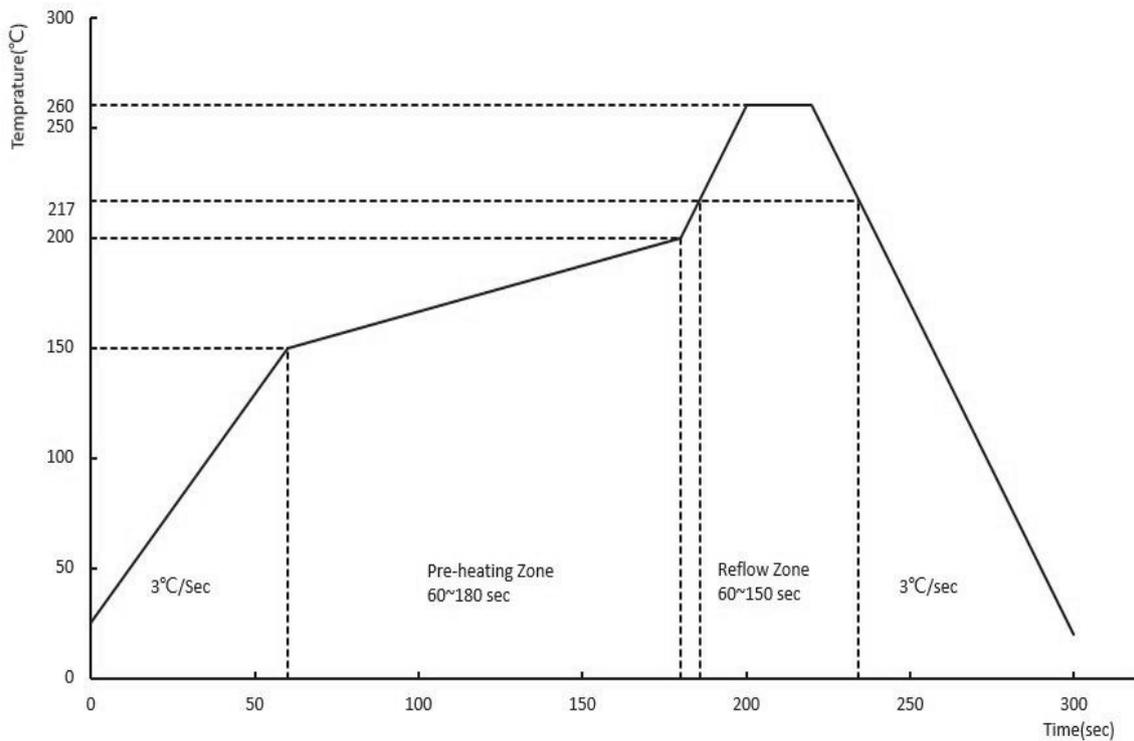
Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 85℃±2℃ , Duration: 250h , Recovery time: 2h±0.5h	
		Temperature: -40℃±3℃ , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60℃±2℃ ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40℃±3℃, TB=85℃±2℃, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245℃±5℃ Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260℃±5℃ , Duration:10±1s	
		Temperature of Soldering Iron: 350℃±10℃, Duration: 3~4s, Recovery time : 2 ± 0.5h	